Sensors and Materials
Special Issue on
Materials, Devices, Circuits, and Analytical Methods for Various Sensors (Selected Papers from ICSEVEN 2020)

Call for Papers

The era of ubiquitous sensing has begun recently thanks to the rapid development of IoT. Sensors are essential components of automotive electronic systems used in modern applications including smart industry, smart city, smart car, robot, smart building and home, and so forth. This issue will focus on all aspects of research and development related to sensor materials, sensor devices, sensor circuits, sensor readout circuits, sensor modules, sensor subsystems or systems, and analytical software, deep learning, and artificial intelligence (AI) for sensor and materials applications. Sensor technology can also be applied to the management of related innovations about data bases and network technologies in business.

We invite authors to contribute their original research as well as comprehensive review articles on the recent progress in all types of materials, devices, circuits, analytical methods, and applications related to various sensors. Potential topics include but are not limited to the following:

- sensor materials,
- sensor devices and sensor arrays/nanosensors/MEMS sensors,
- electrochemical sensors,
- microwave sensors,
- sensor applications to industry, medicine, biosignal monitoring, environmental monitoring, corrosion, and so forth,
- analytical methods, modeling, readout circuits, and software for various sensors,
- deep learning and artificial intelligence (AI) for sensor and materials applications,
- sensor technology and new sensor principles, and
- sensor technology application and innovation issues related to management.

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<th>Manuscript due</th>
<th>Dec. 31, 2020</th>
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<td>First round of reviews</td>
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Lead guest Editor

Chien-Jung Huang, Professor
Department of Applied Physics, National University of Kaohsiung, Taiwan, R.O.C.
Email: chien@nuk.edu.tw
Ja-Hao Chen, Associate Professor
Department of Communications Engineering, Feng Chia University, Taichung, Taiwan, R.O.C.
Email: chiahaoc@fcu.edu.tw

Yu-Ju Lin, Assistant Professor
Department of Industrial Engineering and Enterprise Information, Tunghai University, Taichung, Taiwan, R.O.C.
Email: yujulin@thu.edu.tw

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If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of Sensors and Materials
MYU K.K.
1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan
Tel: +81-3-3827-8549, Fax: +81-3-3827-8547
E-mail: myukk@myu-inc.jp